# **Schottky Barrier Diode**

This Schottky barrier diode is designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

The BAT54M3T5G device is a spin-off of our popular SOT-23 three-leaded device and is housed in the SOT-723 surface mount package. This device is ideal for low-power surface mount applications where board space is at a premium.

#### **Features**

- Extremely Fast Switching Speed
- Low Forward Voltage 0.35 Volts (Typ) @  $I_F = 10 \text{ mAdc}$
- Reduces Board Space
- This is a Halide-Free Device
- This is a Pb-Free Device

### **MAXIMUM RATINGS** (T<sub>J</sub> = 125°C unless otherwise noted)

Rating	Symbol	Value	Unit
Reverse Voltage	V <sub>R</sub>	30	V
Forward Power Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>F</sub>	200 2.0	mW mW/°C
Forward Current (DC)	IF	200 Max	mA
Junction Temperature	TJ	-55 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-55 to +150	°C

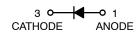
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



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# 30 V SILICON HOT-CARRIER DETECTOR AND SWITCHING DIODE



### MARKING DIAGRAM



SOT-723 CASE 631AA STYLE 2



AP = Specific Device Code M = Date Code

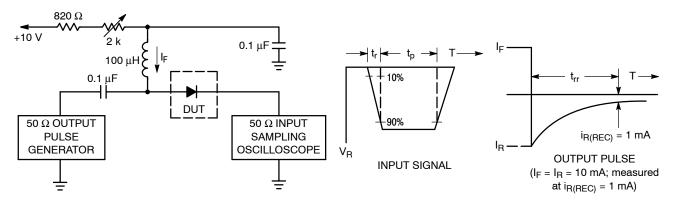
### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
BAT54M3T5G	SOT-723 (Pb-Free)	8000/Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I <sub>R</sub> = 10 μA)	V <sub>(BR)R</sub>	30	-	-	V
Total Capacitance (V <sub>R</sub> = 1.0 V, f = 1.0 MHz)	C <sub>T</sub>	-	7.6	10	pF
Reverse Leakage (V <sub>R</sub> = 25 V)	I <sub>R</sub>	-	0.5	2.0	μΑ
Forward Voltage (I <sub>F</sub> = 0.1 mA)	V <sub>F</sub>	-	0.22	0.24	V
Forward Voltage (I <sub>F</sub> = 1.0 mA)	V <sub>F</sub>	-	0.29	0.32	V
Forward Voltage (I <sub>F</sub> = 10 mA)	V <sub>F</sub>	-	0.35	0.40	V
Forward Voltage (I <sub>F</sub> = 30 mA)	V <sub>F</sub>	-	0.41	0.5	V
Forward Voltage (I <sub>F</sub> = 100 mA)	V <sub>F</sub>	-	0.52	0.8	V
Reverse Recovery Time ( $I_F = I_R = 10 \text{ mA}$ , $I_{R(REC)} = 1.0 \text{ mA}$ , Figure 1)	t <sub>rr</sub>	-	-	5.0	ns



Notes: 1. A 2.0  $k\Omega$  variable resistor adjusted for a Forward Current (IF) of 10 mA.

- 2. Input pulse is adjusted so  $I_{R(peak)}$  is equal to 10 mA.
- 3. t<sub>p</sub> » t<sub>rr</sub>

Figure 1. Recovery Time Equivalent Test Circuit

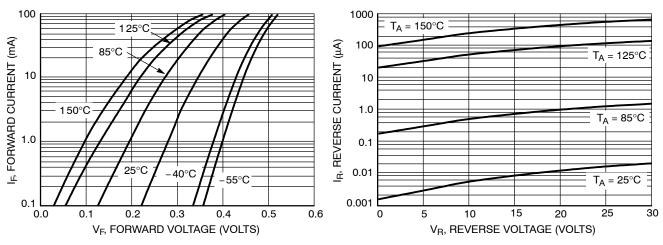


Figure 2. Forward Voltage

Figure 3. Leakage Current

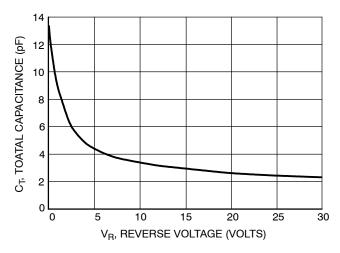
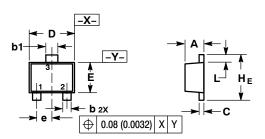


Figure 4. Total Capacitance

### PACKAGE DIMENSIONS

SOT-723 CASE 631AA-01 ISSUE C



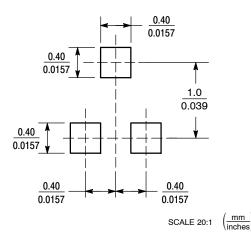
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETERS.
  MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.45	0.50	0.55	0.018	0.020	0.022
b	0.15	0.21	0.27	0.0059	0.0083	0.0106
b1	0.25	0.31	0.37	0.010	0.012	0.015
С	0.07	0.12	0.17	0.0028	0.0047	0.0067
D	1.15	1.20	1.25	0.045	0.047	0.049
E	0.75	0.80	0.85	0.03	0.032	0.034
е	0.40 BSC		0.016 BSC			
ΗE	1.15	1.20	1.25	0.045	0.047	0.049
L	0.15	0.20	0.25	0.0059	0.0079	0.0098

STYLE 2: PIN 1. ANODE 3 CATHODE

### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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